Call for Papers

ICEP 2021
2021 International Conference on Electronics Packaging

Date: May 12 – 14, 2021
Venue: Miraikan (National Museum of Emerging Science and Innovation), Tokyo, Japan
Style: On-site & On-line Hybrid Conference
Please note: The conference style may be changed to Full On-Line depending on the future restrictions on travel
Sponsor: Japan Institute of Electronics Packaging (JIEP)
Technical Co-Sponsors: IEEE EPS Japan Chapter, iMAPS

Conference Topics & Special Notice for Authors

Topic Category 1 (tentative)
Detail of category is TBD, may be modified.
- Advanced Packaging
- Quality, Modeling, and Reliability

Topic Category 2 (tentative)
Detail of category is TBD, may be modified.
- Interconnections
- Materials and Processing

Topic Category 3 (tentative)
Detail of category is TBD, may be modified.
- Optoelectronics
- Power Electronics
- Thermal Management
- Highspeed, Wireless and Components
- Emerging technologies

Oral Presentation
- At the abstract submission, the authors will be asked to choose their preference from: a) On-site live session at Miraikan, or b) On-demand session (video streaming presentation), when their abstracts are accepted for the oral presentations.
- ALL the on-line presenters will be required to prepare the pre-recorded videos of their presentations for backup ONLY when something wrong happens on the streaming.

Poster Presentation
- The posters will be exhibited ON-LINE.
- All the authors will be asked to give on-line short presentations in the poster session.
- Live discussion opportunities will be provided for poster presenters (TBD).

- From the standpoint of being an international non-commercial conference where the public interests are secured, ICEP committee kindly require NOT to record the presentations and discussions in any way, including screen capturing.
- The authors are required to release the copyright of all the submitted contents. For details, visit: https://ux.nu/o27ui

See the backside for details
Abstract submission open: September 1st, 2020
Abstract deadline: November 30th, 2020
Notification of acceptance: January 15th, 2021
Final manuscript deadline: March 1st, 2021

- Authors are encouraged to use the abstract template found at the conference website: http://www.jiep.or.jp/icep/
- Once the abstract is accepted, the author will be required to prepare a 2-pages final paper: For the final paper format, see: http://www.jiep.or.jp/icep/
- Accepted and presented papers will be published in the conference proceedings and submitted to IEEE Xplore as well as other Abstracting and Indexing (A&I) databases (EI Compendex and INSPEC).
- Authors are encouraged to submit their manuscripts to Transactions of The Japan Institute of Electronics Packaging, with enhanced contents of 4 – 10 pages. For details, please see: https://www.jstage.jst.go.jp/browse/jiepeng/-char/en

Important Dates

About ICEP

ICEP is counted as one of the largest Asian international conferences on electronic packaging, attracting more than 400 attendees and hosting over 30 technical sessions every year since 2001. This time, ICEP2021, is the 20th anniversary, being held at Miraikan, Tokyo, Japan, where the attendees will feel an “electric” atmosphere of the Olympic games.

Unfortunately, we had to cancel the last time ICEP due to worldwide COVID-19 situation. However, regarded this experience as a good opportunity to increase the choices of participation measures, ICEP 2021 will take place in an on-site/on-line hybrid system so that global participants can keep joining cutting-edge discussions.

We sincerely hope all the attendees make the most of ICEP 2021 as a cross-cutting platform to dynamize and deepen their R&D activities.

Main Sponsor: Japan Institute for Electronics Packaging (JIEP)
Technical Co-Sponsors: IEEE Electronics Packaging Society (EPS) Japan Chapter, IMAPS

Registration Fee

The details of the registration fee will be announced in the conference HP ASAP when the conference type is finally decided (no later than January 2021).

The following items are included in the registration fee: Receptions, proceedings, and the archive of all 1st to 19th ICEP proceedings as the privilege of the 20th anniversary. How-to-get will be announced in the homepage, too.

Sponsorship Opportunities

The ICEP committee intends to provide cross-disciplinary support for R&D related to electronics packaging technology and is broadly recruiting sponsors who kindly support this idea. Sponsors will receive various benefits in addition to discounted fees. The detail will be announced on the conference website soon.

Contact

ICEP 2021 secretariat (The Japan Institute of Electronics Packaging)
TEL: 03-5310-2010
E-mail: icep2021@jiep.or.jp
URL: http://www.jiep.or.jp/icep/

Outstanding Technical Paper Award

This award recognizes the outstanding papers presented at ICEP. The award will be given to the presenting author and co-authors of the selected papers.

Funding: The award is sponsored by JIEP.
Eligibility: The presenter must be listed as one of the authors. Conference papers must be submitted on or before the due date.
Basis: Papers are reviewed based on: Originality, technical contents, relevance, technical impact of the written paper, and the quality of the conference presentation.

IEEE EPS Japan Chapter Young Award

This award recognizes the excellent papers presented by young scientists and engineers at ICEP. This award will be given to the presenting author.

Funding: The award is sponsored by IEEE EPS Japan Chapter.
Eligibility: The presenter must be listed as one of the authors. The presenter must be younger than 35 years old on December 31 of the presentation year. Previous winners are not eligible. Conference papers must be submitted on or before the due date. The award recipient must be a member of IEEE and EPS at the time the award is received.
Basis: The basis is same as Outstanding Technical Paper Award, with different allocation of points on each item.

JIEP Poster Award

This award recognizes the excellent poster work. The award will be given to the presenting author and co-authors.

Funding: The award is sponsored by JIEP.
Eligibility: The presenter must be listed as one of their paper’s authors. Conference papers must be submitted on or before the due date.
Basis: The basis is same as Outstanding Technical Paper Award, with different allocation of points on each item.

Eiji Higurashi, National Institute of Advanced Industrial Science and Technology (AIST)

Shigenori Aoki, LINTEC corporation
Katsuyuki Miyama, Hokkaido University of Science
Akitsu Shigetou, National Institute for Materials Science (NIMS)

General Chair:
Eiji Higurashi, National Institute of Advanced Industrial Science and Technology (AIST)

General Vice Chairs:
Shigenori Aoki, LINTEC corporation
Katsuyuki Miyama, Hokkaido University of Science
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